TE Internal #: 147444-1

Pin Sockets, Socket Length .23 in [5.84 mm], None, Closed, Through Hole - Press-Fit, Solder, Cable-to-Board, Printed Circuit

Board, Power & Signal

View on TE.com >



Connectors > Socket Connectors > Pin Sockets > Mini Spring Sockets: Closed Bottom, 3A



Socket Length: 5.84 mm [.23 in]

Hole Size (Recommended): 1.02 mm [.04 in]

Solder Process Feature: None
Socket Sleeve Style: Closed

Mating Pin Diameter Range: .33 – .51 mm [.013 – .02 in]

All Mini Spring Sockets: Closed Bottom, 3A (12)

Features

Product Type Features

Socket Sleeve Style	Closed
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Profile	Zero
Product Type	Contact
Body Features	
Sleeve Material	Copper
Sleeve Plating Material	Gold
Contact Features	

Contact Spring Plating Material	Gold
	15 μin
Contact Base Material	Beryllium Copper
Contact Current Rating (Max)	3 A
Socket Type	Discrete
Contact Transmits (Typical)	Signal (Data)/Power
Contact Mating Area Plating Thickness	30 μm[30 μin]



Contact Type	Socket
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Termination Features

Insertion Method	Hand/Semi-Automatic
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Termination Method to Wire & Cable	Solder

Dimensions

Socket Length	5.84 mm[.23 in]
Hole Size (Recommended)	1.02 mm[.04 in]
Mating Pin Diameter Range	.33 – .51 mm[.013 – .02 in]

Operation/Application

Solder Process Feature	None
Circuit Application	Power & Signal

Packaging Features

Packaging Quantity	2000
Packaging Method	Bag

Other

Spring Material	Beryllium Copper

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Pin-in-Paste capable to 260°C

Product Compliance Disclaimer



This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought

















Documents

Product Drawings
SOCKET,MIN-SPR AU-AU SER-1

English

CAD Files
3D PDF



3D

Customer View Model

ENG_CVM_CVM_147444-1_O.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_147444-1_O.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_147444-1_O.3d_stp.zip

English

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Product Specifications

Application Specification

English